

Ordering information									
Device name	Shipping	Package	# of Ports			Pressure type			Device marking
			None	Single	Dual	Gauge	Differential	Absolute	
Small outline package (MPXA6115A series)									
MPXA6115A6U	Rails	98ASB17756C	•					•	MPXA6115A
MPXA6115A6T1	Tape and Reel	98ASB17756C	•					•	MPXA6115A
MPXA6115AC6U	Rails	98ASB17757C		•				•	MPXA6115A
MPXA6115AC6T1	Tape and Reel	98ASB17757C		•				•	MPXA6115A
MPXA6115AC7U	Rails	98ASB17759C		•				•	MPXA6115A
Small outline package (Media resistant gel) (MPXAZ6115A series)									
MPXAZ6115AC6T1	Tape and Reel	98ASB17757C		•				•	MPXAZ6115A
MPXAZ6115AP	Trays	98ASA99303D		•				•	MPXAZ6115A
MPXAZ6115APT1	Tape and Reel	98ASA99303D		•				•	MPXAZ6115A
Super small outline package (MPXH6115A series)									
MPXH6115A6U	Rails	98ARH99066A	•					•	MPXH6115A
MPXH6115A6T1	Tape and Reel	98ARH99066A	•					•	MPXH6115A
MPXH6115AC6U	Rails	98ARH99089A		•				•	MPXH6115A
MPXH6115AC6T1	Tape and Reel	98ARH99089A		•				•	MPXH6115A
Small outline package (Media resistant gel) (MPXHZ6115A series)									
MPXHZ6115A6U	Rails	98ARH99066A	•					•	MPXHZ6115A
MPXHZ6115A6T1	Tape and Reel	98ARH99066A	•					•	MPXHZ6115A
MPXHZ6115AC6U	Rails	98ARH99089A		•				•	MPXHZ6115A
MPXHZ6115AC6T1	Tape and Reel	98ARH99089A		•				•	MPXHZ6115A

MPXA6115A



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Related Documentation

The MPXxx6115A device features and operations are described in a variety of reference manuals, user guides, and application notes. To find the most-current versions of these documents:

1. Go to the Freescale homepage at:
<http://www.freescale.com/>
2. In the Keyword search box at the top of the page, enter the device number MPXxx6115A.
3. In the Refine Your Result pane on the left, click on the Documentation link.

1 General Description

1.1 Block diagram

Figure 1 shows a block diagram of the internal circuitry integrated on a pressure sensor chip.

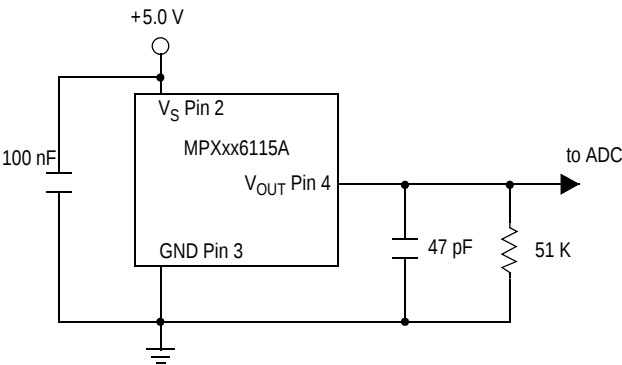


Figure 1. Fully integrated pressure sensor schematic

1.2 Pinout

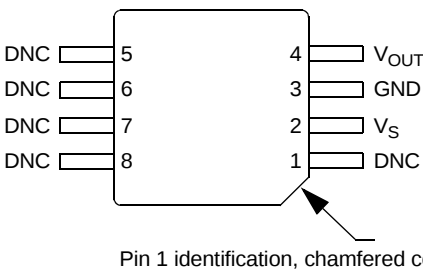


Figure 2. Device pinout (top view)

Table 1. Pin functions

Pin	Name	Function
1	DNC	Do not connect to external circuitry or ground. Pin 1 is denoted by chamfered corner.
2	V _S	Voltage supply
3	GND	Ground
4	V _{OUT}	Output voltage
5	DNC	Do not connect to external circuitry or ground.
6	DNC	Do not connect to external circuitry or ground.
7	DNC	Do not connect to external circuitry or ground.
8	DNC	Do not connect to external circuitry or ground.

2 Mechanical and Electrical Specifications

2.1 Maximum ratings

Table 2. Maximum ratings⁽¹⁾

Rating	Symbol	Value	Units
Maximum pressure (P1 > P2)	P_{max}	400	kPa
Storage temperature	T_{stg}	-40° to +125°	°C
Operating temperature	T_A	-40° to +125°	°C
Output source current @ full-scale output ⁽²⁾	I_{o+}	0.5	mAdc
Output sink current @ minimum pressure offset ⁽²⁾	I_{o-}	-0.5	mAdc

1.Exposure beyond the specified limits may cause permanent damage or degradation to the device.

2.Maximum output current is controlled by effective impedance from V_{OUT} to GND or V_{OUT} to V_S in the application circuit.

2.2 Operating characteristics

Table 3. Operating characteristics ($V_S = 5.0$ Vdc, $T_A = 25$ °C unless otherwise noted, P1 > P2)

Characteristic	Symbol	Min	Typ	Max	Unit
Pressure range	P_{OP}	15	—	115	kPa
Supply voltage ⁽¹⁾	V_S	4.75	5.0	5.25	Vdc
Supply current	I_o	—	6.0	10	mAdc
Minimum pressure offset ⁽²⁾ (0 °C to 85° C) @ $V_S = 5.0$ Volts	V_{off}	0.133	0.200	0.268	Vdc
Full-scale output ⁽³⁾ (0 °C to 85° C) @ $V_S = 5.0$ Volts	V_{FSO}	4.633	4.700	4.768	Vdc
Full-scale span ⁽⁴⁾ (0 °C to 85° C) @ $V_S = 5.0$ Volts	V_{FSS}	4.433	4.500	4.568	Vdc
Accuracy ⁽⁵⁾ (0 °C to 85° C)	—	—	—	±1.5	% V_{FSS}
Sensitivity	V/P	—	45.0	—	mV/kPa
Response time ⁽⁶⁾	t_R	—	1.0	—	ms
Warm-up time ⁽⁷⁾	—	—	20	—	ms
Offset stability ⁽⁸⁾	—	—	±0.25	—	% V_{FSS}

1.Device is ratiometric within this specified excitation range.

2.Offset (V_{off}) is defined as the output voltage at the minimum rated pressure.

3.Full-scale output (V_{FSO}) is defined as the output voltage at the maximum or full-rated pressure.

4.Full-scale span (V_{FSS}) is defined as the algebraic difference between the output voltage at full-rated pressure and the output voltage at the minimum rated pressure.

5.Accuracy is the deviation in actual output from nominal output over the entire pressure range and temperature range as a percent of span at 25 °C due to all sources of error including the following:

Linearity: Output deviation from a straight line relationship with pressure over the specified pressure range.

Temperature Hysteresis: Output deviation at any temperature within the operating temperature range, after the temperature is cycled to and from the minimum or maximum operating temperature points, with zero differential pressure applied.

Pressure Hysteresis: Output deviation at any pressure within the specified range, when this pressure is cycled to and from minimum or maximum rated pressure at 25 °C.

TcSpan: Output deviation over the temperature range of 0 °C to 85 °C, relative to 25 °C.

TcOffset: Output deviation with minimum pressure applied, over the temperature range of 0 °C to 85 °C, relative to 25 °C.

6.Response time is defined as the time for the incremental change in the output to go from 10% to 90% of its final value when subjected to a specified step change in pressure.

7.Warm-up time is defined as the time required for the product to meet the specified output voltage after the pressure has been stabilized.

8.Offset stability is the product's output deviation when subjected to 1000 cycles of pulsed pressure, temperature cycling with bias test.

3 On-chip Temperature Compensation and Calibration

Figure 3 illustrates the absolute sensing chip in the basic super small outline chip carrier (case 98ARH99066A).

Figure 4 shows a typical application circuit (output source current operation).

Figure 5 shows the sensor output signal relative to pressure input. Typical minimum and maximum output curves are shown for operation over 0 °C to 85 °C temperature range. The output will saturate outside of the rated pressure range.

A fluorosilicone gel isolates the die surface and wire bonds from the environment, while allowing the pressure signal to be transmitted to the silicon diaphragm. The MPXxx6115A series pressure sensor operating characteristics, internal reliability and qualification tests are based on use of dry air as the pressure media. Media other than dry air may have adverse effects on sensor performance and long-term reliability. Contact the factory for information regarding media compatibility in your application.

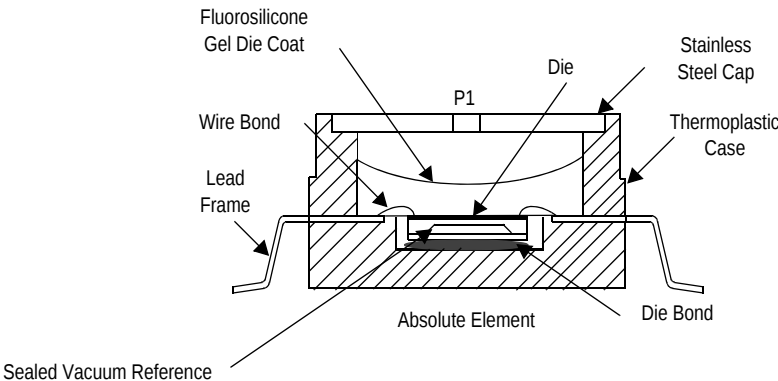


Figure 3. Cross Sectional Diagram SSOP/SOP (not to scale)

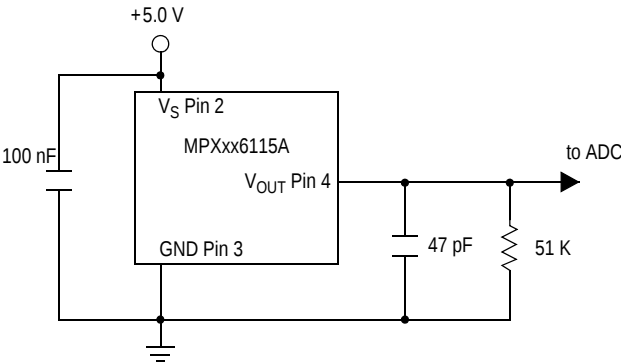


Figure 4. Typical application circuit (output source current operation)

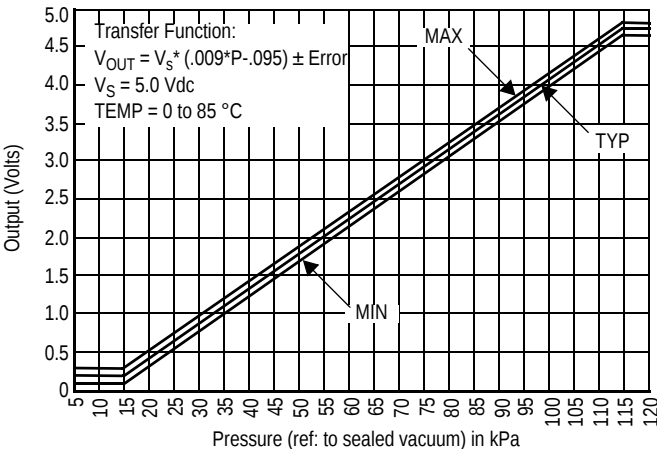


Figure 5. Output vs. absolute pressure

MPXA6115A

Nominal Transfer Value: $V_{OUT} = V_S \times (0.009 \times P - 0.095)$
 $\pm (\text{Pressure Error} \times \text{Temp. Factor} \times 0.009 \times V_S)$
 $V_S = 5.0 \pm 0.25 \text{ Vdc}$

Figure 6. Transfer function

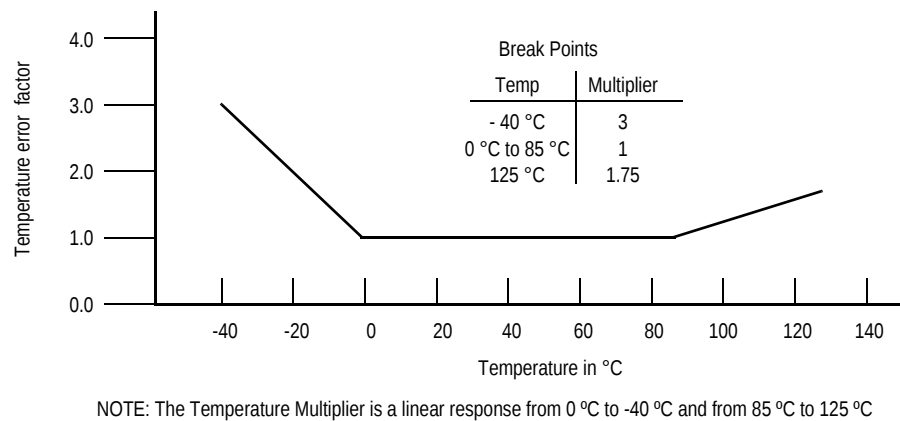


Figure 7. Temperature error band

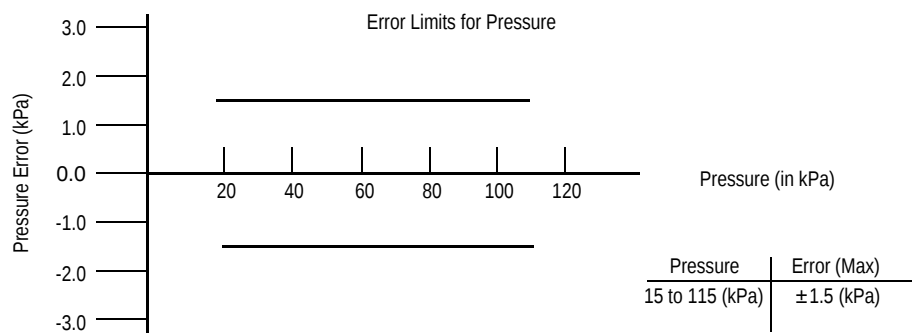


Figure 8. Pressure error band

4 Package Information

4.1 Minimum recommended footprint for small and super small packages

Surface mount board layout is a critical portion of the total design. The footprint for the semiconductor package must be the correct size to ensure proper solder connection interface between the board and the package. With the correct pad geometry, the packages will self-align when subjected to a solder reflow process. It is always recommended to fabricate boards with a solder mask layer to avoid bridging and/or shorting between solder pads, especially on tight tolerances and/or tight layouts.

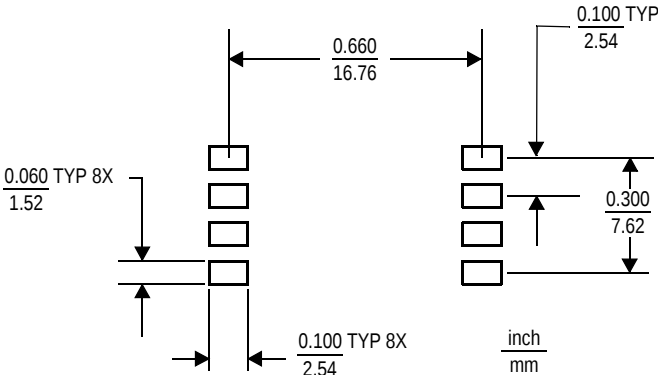


Figure 9. SOP Footprint (Case 98ASB17756C)

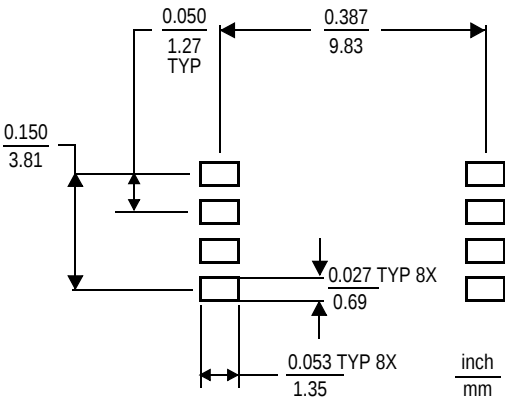
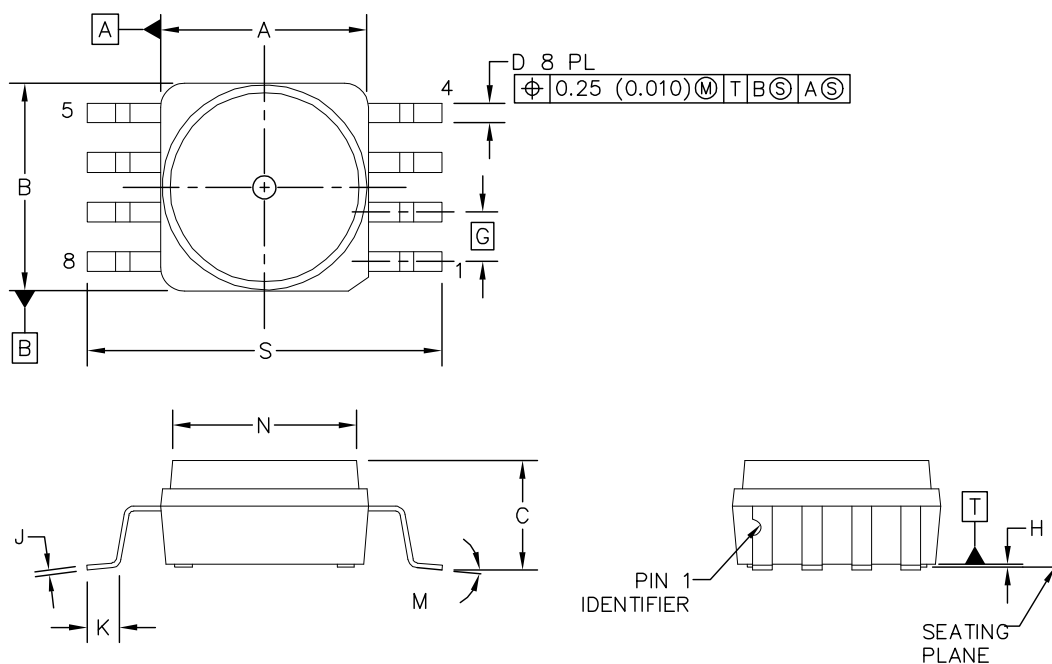


Figure 10. SSOP Footprint (Case 98ARH99066A and 98ARH99089A)

4.2 Package dimensions

This drawing is located at http://cache.freescale.com/files/shared/doc/package_info/98ASB17756C.pdf.



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	10.54	10.79	0.415	0.425
B	10.54	10.79	0.415	0.425
C	5.38	5.84	0.212	0.230
D	0.96	1.07	0.038	0.042
G	2.54 BSC		0.100 BSC	
H	0.05	0.25	0.002	0.010
J	0.23	0.28	0.009	0.011
K	1.55	1.80	0.061	0.071
M	0°	7°	0°	7°
N	10.29	10.54	0.405	0.415
S	18.01	18.41	0.709	0.725

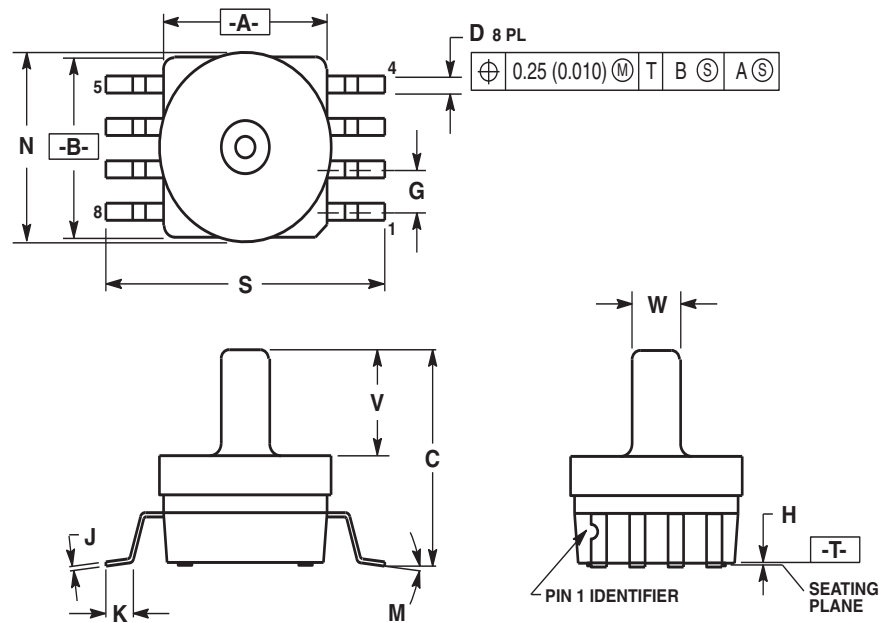
NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION "A" AND "B" DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006).
5. ALL VERTICAL SURFACES 5° TYPICAL DRAFT.

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TITLE: 8 LD SENSOR SOP		DOCUMENT NO: 98ASB17756C	REV: A
		STANDARD: NON-JEDEC	
			10 JAN 2013

Case 98ASB17756C, Small outline package

MPXA6115A

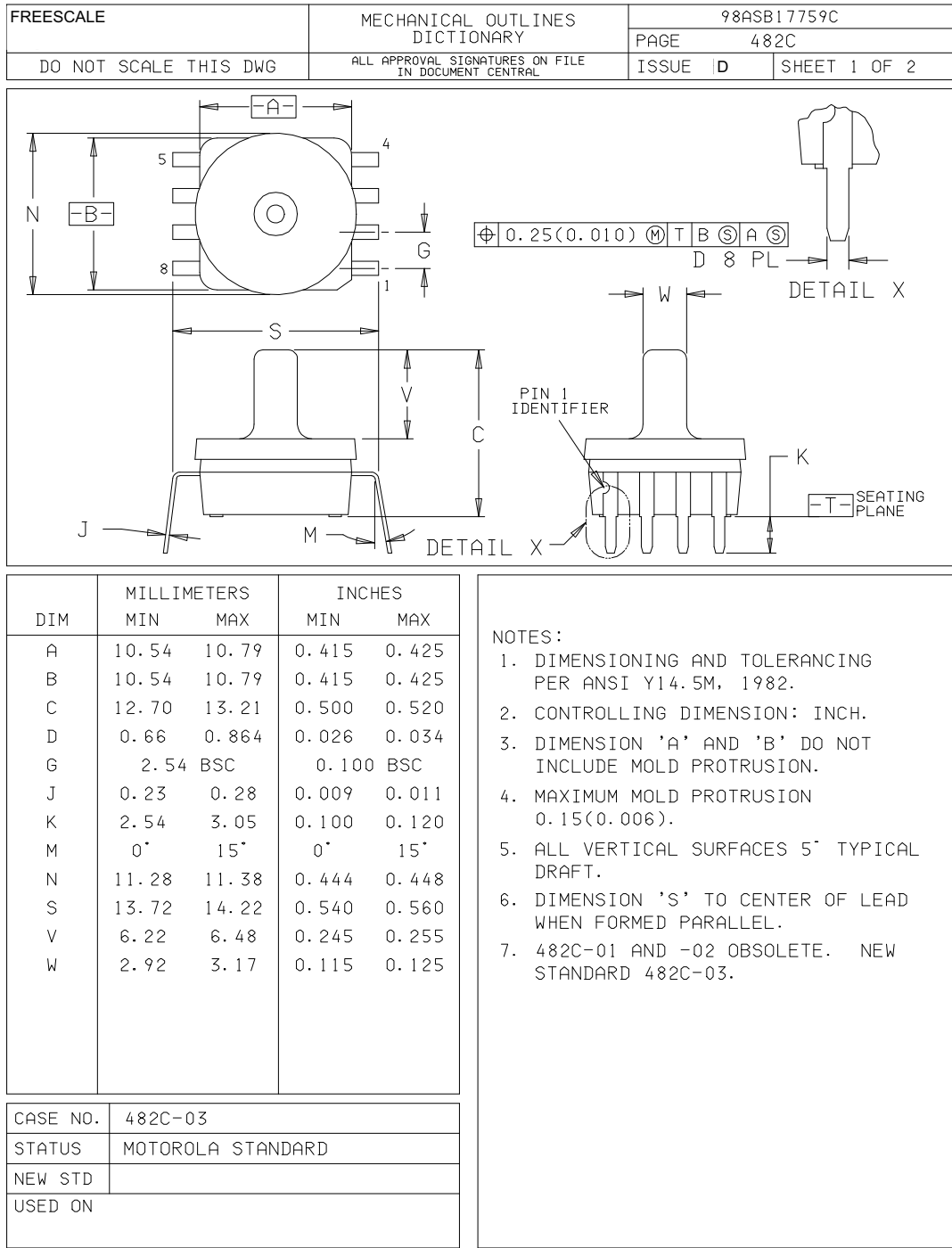


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006).
5. ALL VERTICAL SURFACES 5° TYPICAL DRAFT.

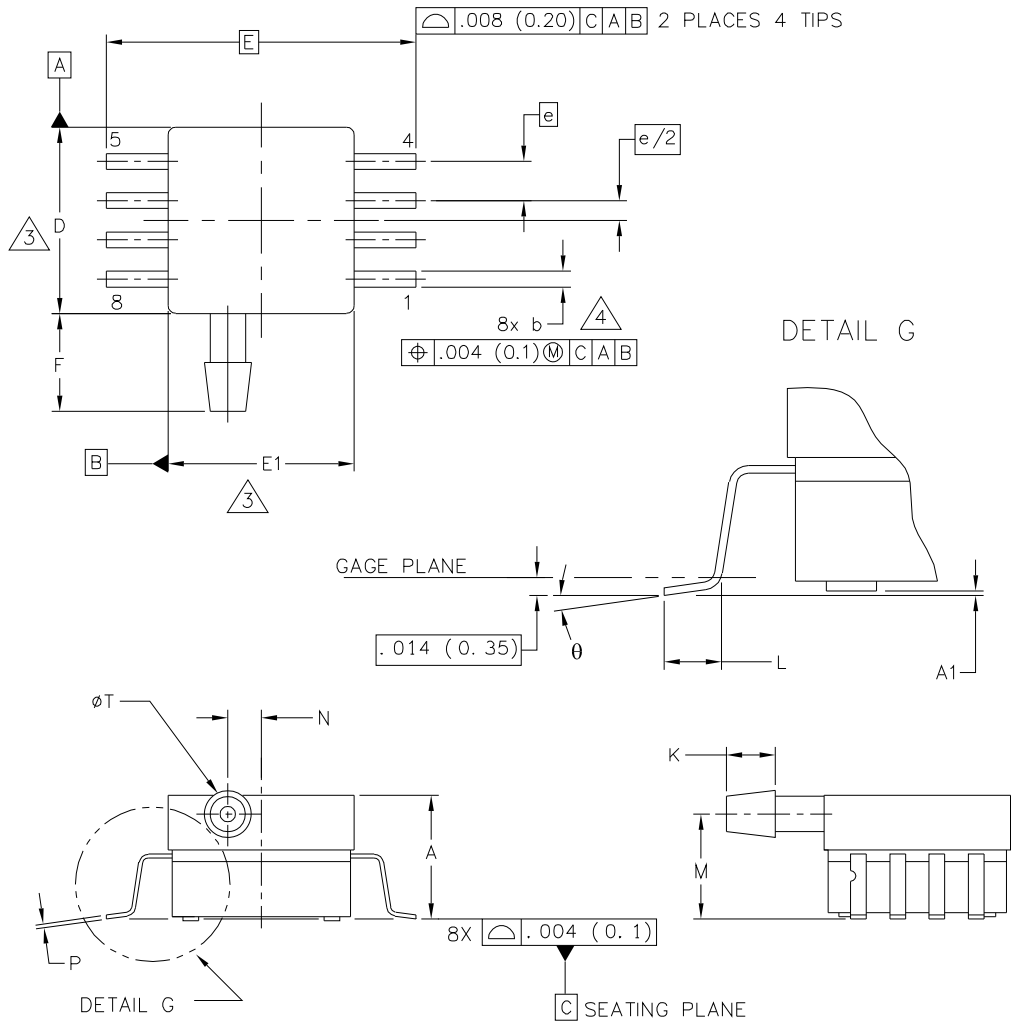
DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.415	0.425	10.54	10.79
B	0.415	0.425	10.54	10.79
C	0.500	0.520	12.70	13.21
D	0.038	0.042	0.96	1.07
G	0.100 BSC		2.54 BSC	
H	0.002	0.010	0.05	0.25
J	0.009	0.011	0.23	0.28
K	0.061	0.071	1.55	1.80
M	0"	7"	0"	7"
N	0.444	0.448	11.28	11.38
S	0.709	0.725	18.01	18.41
V	0.245	0.255	6.22	6.48
W	0.115	0.125	2.92	3.17

Case 98ASB17757C, small outline package



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Case 98ASB17759C, small outline package



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TITLE: 8 LD SOP, SIDE PORT		DOCUMENT NO: 98ASA99303D		REV: D	
		CASE NUMBER: 1369-01		13 DEC 2010	
		STANDARD: NON-JEDEC			

NOTES:

1. CONTROLLING DIMENSION: INCH

2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.

3. DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS.
MOLD FLASH AND PROTRUSIONS SHALL NOT EXCEED .006 (0.152) PER SIDE.

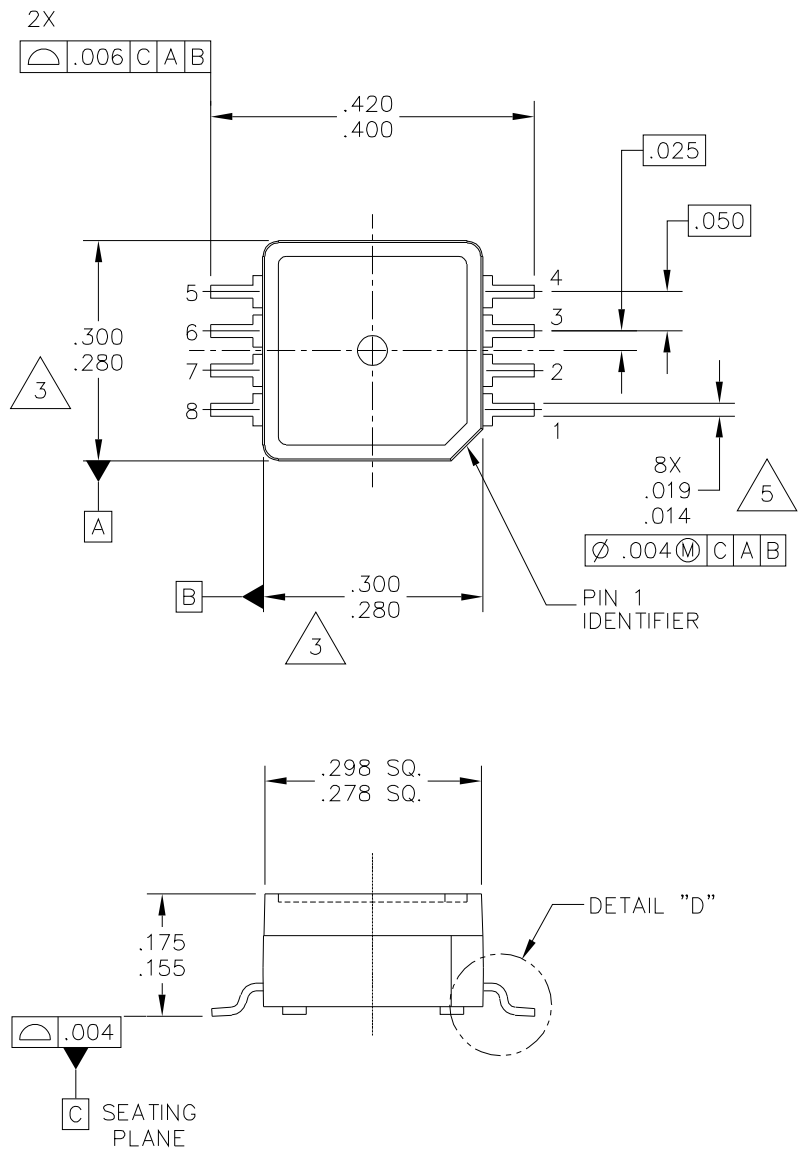
4. DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE .008 (0.203) MAXIMUM.

DIM	INCHES		MILLIMETERS		DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX		MIN	MAX	MIN	MAX
A	.300	.330	7.62	8.38	Ø	0°	7°	0°	7°
A1	.002	.010	0.05	0.25	—	---	---	---	---
b	.038	.042	0.96	1.07	—	---	---	---	---
D	.465	.485	11.81	12.32	—	---	---	---	---
E	.717 BSC		18.21 BSC		—	---	---	---	---
E1	.465	.485	11.81	12.32	—	---	---	---	---
e	.100 BSC		2.54 BSC		—	---	---	---	---
F	.245	.255	6.22	6.47	—	---	---	---	---
K	.120	.130	3.05	3.30	—	---	---	---	---
L	.061	.071	1.55	1.80	—	---	---	---	---
M	.270	.290	6.86	7.36	—	---	---	---	---
N	.080	.090	2.03	2.28	—	---	---	---	---
P	.009	.011	0.23	0.28	—	---	---	---	---
T	.115	.125	2.92	3.17	—	---	---	---	---
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TITLE: 8 LD SOP, SIDE PORT					DOCUMENT NO: 98ASA99303D			REV: D	
					CASE NUMBER: 1369-01			13 DEC 2010	
					STANDARD: NON-JEDEC				

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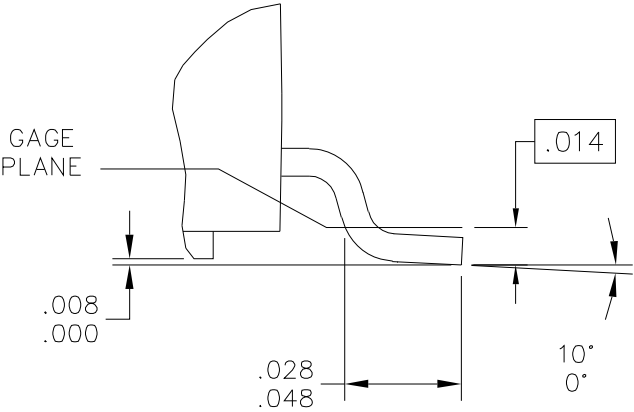
Case 98ASA99303D, Small outline package

MPXA6115A



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TITLE: 8 LEAD SSOP		DOCUMENT NO: 98ARH99066A		REV: H	
		CASE NUMBER: 1317-04		13 APR 2012	
		STANDARD: NON-JEDEC			

Case 98ARH99066A, Super small outline package



DETAIL "D"

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		CASE NUMBER: 1317-04		13 APR 2012	
		STANDARD: NON-JEDEC			

Case 98ARH99066A, Super small outline package

NOTES:

1. ALL DIMENSIONS IN INCHES.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.

3. DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS.
MOLD FLASH OR PROTRUSION SHALL NOT EXCEED .006 INCHES PER SIDE.

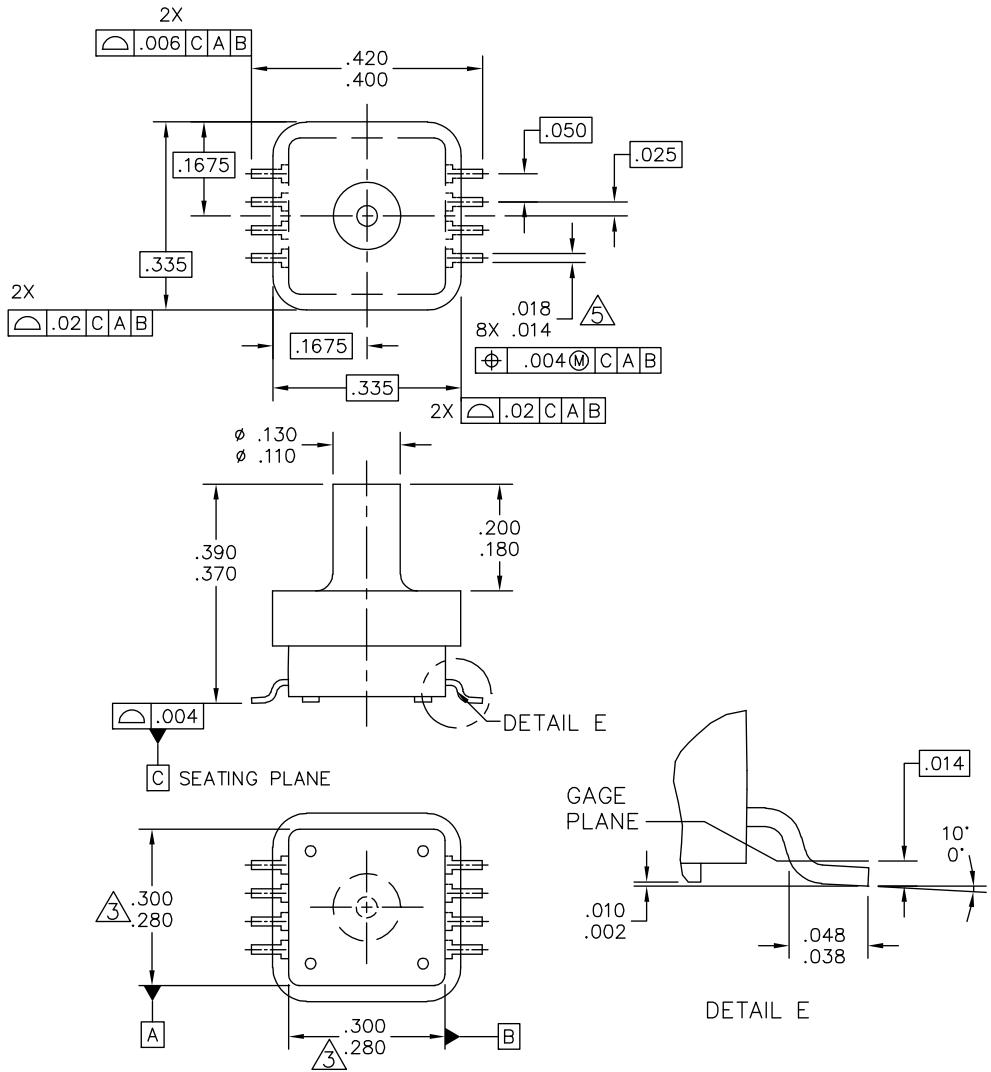
4. ALL VERTICAL SURFACES TO BE 5° MAXIMUM.

5. DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION.
ALLOWABLE DAMBAR PROTRUSION SHALL BE .008 INCHES MAXIMUM.

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TITLE: 8 LEAD SSOP			DOCUMENT NO: 98ARH99066A		REV: H
			CASE NUMBER: 1317-04		13 APR 2012
			STANDARD: NON-JEDEC		

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Case 98ARH99066A, Super small outline package



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TITLE: 8 LD, PORTED SSOP		DOCUMENT NO: 98ARH99089A		REV: D	
		CASE NUMBER: 1317A-04		26 OCT 2006	
		STANDARD: NON-JEDEC			

NOTES:

1. ALL DIMENSIONS IN INCHES.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS.
MOLD FLASH OR PROTRUSION SHALL NOT EXCEED .006 INCHES PER SIDE.
4. ALL VERTICAL SURFACES TO BE 5° MAXIMUM.
5. DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION.
ALLOWABLE DAMBAR PROTRUSION SHALL BE .008 INCHES MAXIMUM.

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TITLE: 8 LD, PORTED SSOP		DOCUMENT NO: 98ARH99089A		REV: D	
		CASE NUMBER: 1317A-04		26 OCT 2006	
		STANDARD: NON-JEDEC			

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Case 98ARH99089A, Super small outline package

5 Revision History

Table 4. Revision history

Revision number	Revision date	Description of changes
7.1	05/2012	Updated Package Drawing 98ARH99066A was Rev. F, updated to Rev. H,
7.2	10/2012	On page 1, changed typical output voltage from 4.8V to 4.7V to match typical output voltage listed on page 3 of document
7.3	04/2015	- Removed obsolete part numbers MPXAZ6115A6U and MPXAZ6115AC6U from data sheet. - Updated format.

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Document Number: MPXA6115A

Rev. 7.3

04/2015

